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The Government of the Hong Kong Special Administrative Region
Intellectual Property Department

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Patents Form SP2

Request for a copy of document

Patents Ordinance (Cap. 514)
Patents (General) Rules (Cap. 514C)

Important notes

1. General notes:

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- c. This form must be signed and dated.
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5. Submission of application/request/notice:

In person or by mail to the Registrar of Patents, 24/F, Wu Chung House, No. 213 Queen's Road East, Wanchai, Hong Kong, China.

DRAFT

*Denotes mandatory fields

01. Reference

Filer's reference

02. *Details of the request

Application No. / Patent No.

Details of the document/
information requested

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No. of pages

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03. *Details of contact person(s)

Please provide the details of the contact person in Hong Kong, China for collection of the documents.

***(a) Name**

***(b) Address**

You must provide details of an address in Hong Kong, China. Please note that a P.O. Box, a “care of” address or an address used solely for mail forwarding is not acceptable.

Flat/Floor/Building

Street/District

HONG KONG, CHINA

***(c) Telephone no.**

In Hong Kong, China

***(d) Fax no.**

In Hong Kong, China

04. *Signature

I/We confirm that I/we have read, understood and agreed to abide by the “Important notes” of this form.

***(a) Authorized signature**

***(b) Name of signatory**

***(c) Official capacity of signatory**

Examples: Authorized person, Director, Partner or Principal Officer of Applicant(s)/Proprietor(s)/Agent; Applicant/Proprietor in person

***(d) Date**

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